

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT6940686

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	JU LEE	09/27/2021
	SEUNG HEON LEE	09/27/2021
	SUNG HONG WON	09/27/2021
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PROPERTY NUMBERS Total: 1		
Property Type	Number	
Application Number:	17438087	
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NAME OF SUBMITTER:	IRENE REE	
SIGNATURE:	/IRENE REE/	
DATE SIGNED:	09/28/2021	
Total Attachments: 2		
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ASSIGNMENT

WHEREAS I/We, the below named inventor(s) (hereinafter referred to as Assignor(s)), have made an invention entitled:

**COIL ASSEMBLY OF SLOTLESS MOTOR, HOUSING AND SLOTLESS MOTOR
INCLUDING THE SAME**

for which I/WE executed an application for United States Letters Patent that was filed or will be filed in the United States Patent and Trademark Office; and

WHEREAS, IUCF-HYU (Industry-University Cooperation Foundation Hanyang University), a corporation of Republic of Korea, whose post office address is (Inside Hanyang University, Haengdang-dong) 222, Wangsimni-ro Seongdong-gu Seoul 04763 Republic of Korea (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from Assignee(s) is hereby acknowledged, I/We, as Assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the Assignee(s), its/their lawful successors and assigns, my/our entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/We hereby authorize and request the Director of United States Patent and Trademark Office to issue all Letters Patent for this invention to Assignee(s), its/their successors and assigns, in accordance with the terms of this Assignment;

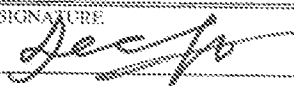
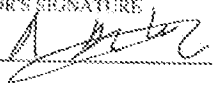
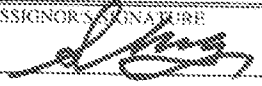
AND, I/WE HEREBY covenant that I/We have the full right to convey the interest assigned by this Assignment, and I/We have not executed and will not execute any agreement in conflict with this Assignment;

AND, I/WE HEREBY further covenant and agree that I/We will, without further consideration, communicate with Assignee(s), its/their successors and assigns, any facts known to me/us respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so.

execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said Assignee(s), its/their successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee(s), its/their successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee(s), its/their successors and assigns.

AND, I/WE HEREBY authorize and request the attorneys I/we have empowered in the Power of Attorney in this application, to insert here in parentheses (Application No. 17/438,087, filed on September 10, 2021) the filing date and application number of said application when known.

IN TESTIMONY WHEREOF, I/We have hereunto set our hands.

1. FULL NAME OF SOLE OR FIRST ASSIGNOR LEE, Ju	ASSIGNOR'S SIGNATURE 	DATE 2021.09.27
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PATENT

RECORDED: 09/28/2021

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